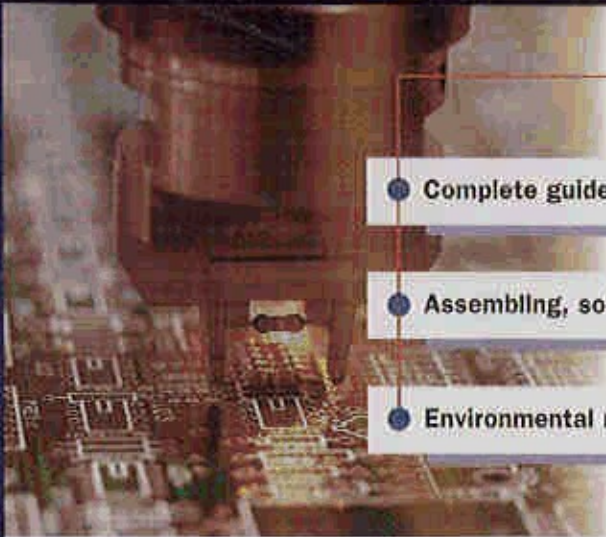


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**PROFESSIONAL
ENGINEERING**

- 
- Complete guide through the fabrication processes
 - Assembling, soldering, cleaning, and coating
 - Environmental rules and constraints

Electronic Assembly Fabrication

CHIPS, CIRCUIT BOARDS,
PACKAGES, AND COMPONENTS

Charles A. Harper

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